

22 DEC 2004

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
22 January 2004 (22.01.2004)

PCT

(10) International Publication Number
WO 2004/008497 A3

- (51) International Patent Classification⁷: B32B 15/06, 15/16, 15/20, 25/02, 25/04, 25/20, 31/00, H05K 7/20
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- (21) International Application Number: PCT/US2003/022710
- (22) International Filing Date: 15 July 2003 (15.07.2003)
- (25) Filing Language: English
- (26) Publication Language: English
- (30) Priority Data: 60/396,294 15 July 2002 (15.07.2002) US
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- (81) Designated States (national): AE, AG, AL, AM, AT (utility model), AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ (utility model), CZ, DE (utility model), DE, DK (utility model), DK, DM, DZ, EC, EE (utility model), EE, ES, FI (utility model), FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NI, NO, NZ, OM, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK (utility model), SK, SL, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.
- (84) Designated States (regional): ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).
- Published:
— with international search report
— before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments
- (88) Date of publication of the international search report: 1 April 2004
- For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: THERMAL INTERCONNECT AND INTERFACE SYSTEMS, METHODS OF PRODUCTION AND USES THEREOF

(57) Abstract: Layered thermal components described herein include at least one thermal interface component and at least one heat spreader component coupled to the thermal interface component. A method of forming layered thermal components disclosed herein comprises: a) providing at least one thermal interface component; b) providing at least one heat spreader component; and c) physically coupling the at least one thermal interface component and the at least one heat spreader component. At least one additional layer, including a substrate layer, can be coupled to the layered thermal component. A method for forming the thermal interface components disclosed herein comprises a) providing at least one saturated rubber compound, b) providing at least one amine resin, c) crosslinking the at least one saturated rubber compound and the at least one amine resin to form a crosslinked rubber-resin mixture, d) adding at least one thermally conductive filler to the crosslinked rubber-resin mixture, and e) adding a wetting agent to the crosslinked rubber-resin mixture. This method can also further comprise adding at least one phase change material to the thermal interface component. A suitable interface material can also be produced that comprises at least one solder material. Additionally, a suitable interface material can be produced that comprises at least one solder material and at least one resin component.

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